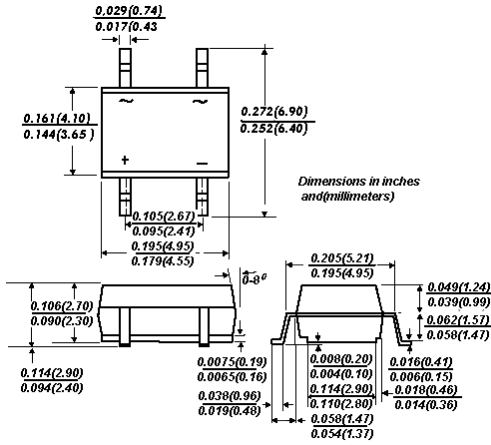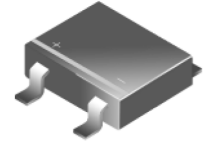# 表面贴装整流桥 S1ZB20 thru S1ZB100

Miniature Glass Passivated Single-Phase Surface Mount Bridge Rectifier
Reverse Voltage 200 to 1000V Forward Current 0.8A

FEATURES

◆ 表面贴装应用

◆ 塑料封装（MBS）

◆ 玻璃钝化芯片

◆ 高浪涌电流 30A

◆ 最高焊接温度 260℃ /10 秒

MECHANICAL DATA

◆ 封装: 塑料封装:

◆ 焊接端子: 锡镀层

◆ 包装: 36K/箱　3 K / Reel（13"）

◆ 重量: 0.125g

MAXIMUM RATINGS AND THERMAL CHARACTERISTICS

Ratings at 25℃ ambient temperature unless otherwise specified.

	Symbols	S1ZB20	S1ZB40	S1ZB60	S1ZB80	S1ZB100	Units
Maximum recurrent peak reverse Voltage	V_{RRM}	200	400	600	800	1000	Volts
Maximum RMS voltage	V_{RMS}	140	280	420	560	700	Volts
Maximum DC blocking voltage	V_{DC}	200	400	600	800	1000	Volts
Maximum average forward output rectified current (see Fig :1)　　　on glass-epoxy P.C.B. (1)　　　on aluminum substrate (2)	$I_{F(AV)}$	0.5 0.8					Amps
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30.0					Amps
Maximum instantaneous forward voltage drop per leg at 0.5A	V_F	1.1					Volts
Maximum DC reverse current T_A=25℃　at rated DC blocking voltage T_A=125℃	I_R	5.0 100.0					μA
Rating for fusing (t<8.3ms)	I^2t	5.0					A^2sec
Typical junction capacitance per leg at 4.0V.1MHz	C_J	13.0					pF
Typical thermal resistance per leg	$R_\Theta JL$ $R_\Theta JA$ $R_\Theta JA$	20.0 85.0[1] 70.0[2]					℃/W
Operating junction and storage temperature range	$T_J T_{STG}$	-55 to+150					℃

NOTES:

　　1. On glass epoxy P.C.B. mounted on0.05*0.05"(1.3*1.3mm)pads

　　2. On aluminum substrate P.C.B. with an area of 0.8"(20*20mm) mounted
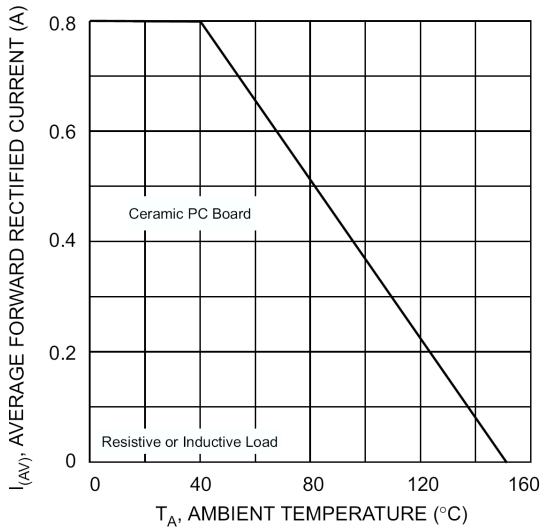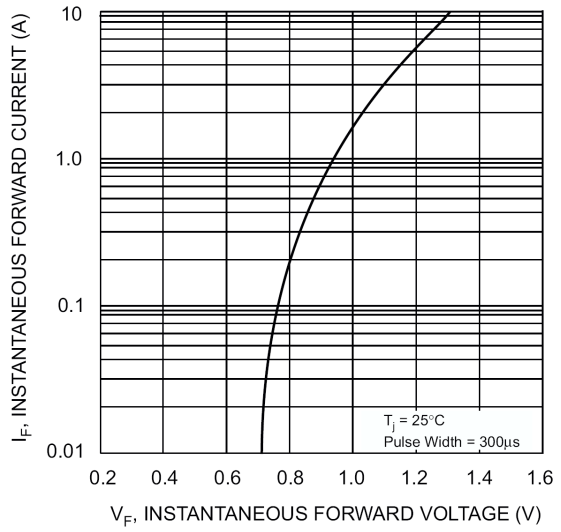
Fig. 1 Output Current Derating Curve

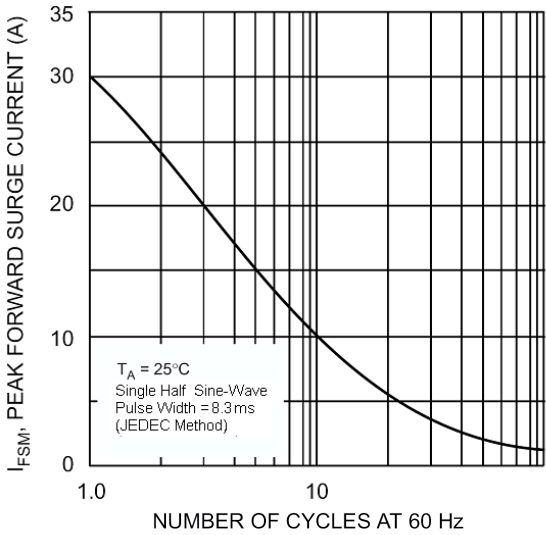Fig. 2 Typical Forward Characteristics (per leg)
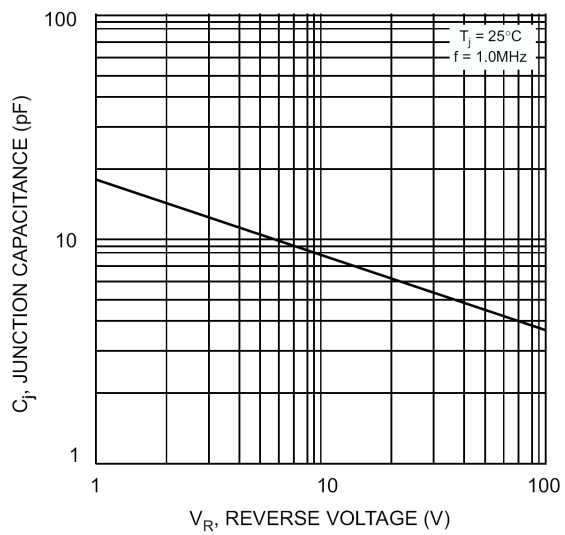
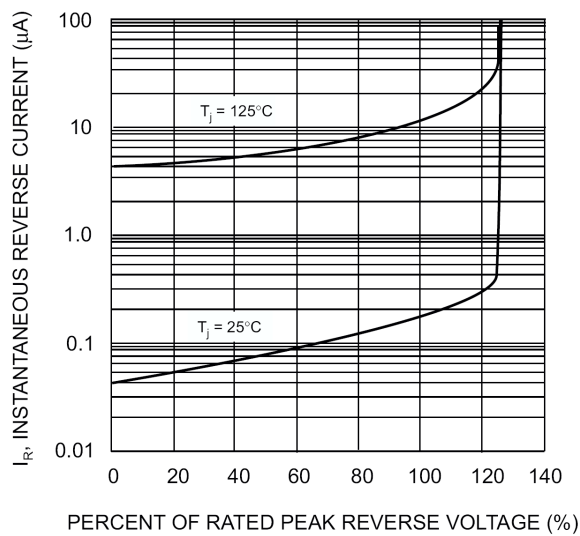Fig. 3 Maximum Peak Forward Surge Current (per leg)

Fig. 4 Typical Junction Capacitance

Fig. 5 Typical Reverse Characteristics (per element)